



喬訊電子工業股份有限公司  
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|---------------------------------------------------------------------------------------------------------------|-----------------------|------------------|---------------------------------|
| Type Document                                                                                                 | Product Specification | Revised /Edition | G                               |
| Date Issued                                                                                                   | 2005/05/05            | Data Revised     | 2016/09/10                      |
| Subject: JS-1102-xx JS-1103-xx(B) JS-1102-T JS-1102-T(L)<br>Pitch 5.00mm Series Wire to Board Power Connector |                       |                  | Issued By:<br>Engineering Dept. |

*This specification is referred to 5.00mm DIP series wire to board Power connector.*

本規格書內容係提供 5.00 mm DIP 系列產品相關參考，  
其用途為電線端相接於電路板端動力電源連接器

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| REV. (版次) | Revision Record (改版變更原因)                                                                                                                                                                                               | Date(日期)   | ECN No.       |
|-----------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|------------|---------------|
| G         | 修改8.10.1溫度曲線原265°C改為250°C                                                                                                                                                                                              | 2016/09/10 | EC2016-09-010 |
| F         | 1.修訂8.10.1 項 Temperature Profile / 2增訂8.7 項Cold耐寒試驗                                                                                                                                                                    | 2015/02/25 | EC2015-02-025 |
| E         | 1.依據CSA C22.2 No.182.3 修訂6.2 項 Wire Pullout Force(Axial) 2.增訂Wave Peak Soldering In- Process Temperature Profile 3.修訂Solder Ability 附註Tin Plated : 95% / Gold Plated : 75% 4增訂3.5項Storage of Package以及 3.6 項Floor Life | 2014/02/06 | EC2014-02-006 |
| D         | 1.增加耐久性 及溫升 2.刪除硫化氫 3.修正(EIA-364) 參考規範 4. 增列額定電壓 及電流 與AWG對照                                                                                                                                                            | 2012/03/08 | EC2012-03-007 |
| C         | 鹽水噴霧週期以電鍍方式區隔為 8 小時與48 小時                                                                                                                                                                                              | 2011/05/06 | EC2011-05-016 |
| B         | 增加中文敘述 以及增加版次變更註記欄                                                                                                                                                                                                     | 2010/03/03 | EC2010-03-02  |



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1.0 Product Name/Part Number & Drawing Number(產品名稱 / 產品型號及圖面型號):

| Product Name(產品名稱) |                          | Part Number(零件型號) | Drawing Number(圖面型號) |
|--------------------|--------------------------|-------------------|----------------------|
| Crimp Terminal     | Standard Feed (鍍型端子直向進料) |                   | JS-1102-T            |
|                    | Side Feed (側邊料帶橫向進料)     |                   | JS-1102-T(L)         |
| Housing            |                          |                   | JS-1102-XX           |
| Wafer              |                          |                   | JS-1103-XX(B)        |

Note: (xx) The number of the circuits.

2.0 Construction/Dimensions/Material & Surface Finish(材質以及表面鍍層):

| Part Name(零件名稱)       |                     | Material(材質)            | Surface Finish(表面鍍層)                             |
|-----------------------|---------------------|-------------------------|--------------------------------------------------|
| Crimp Terminal (柳壓端子) |                     | Brass                   | Tin-Plated<br>(Stamping after tin plated 先電鍍後沖壓) |
| Housing(電線端連接器)       |                     | Nylon 66                | UL 94V-0                                         |
| Wafer<br>(電路板端連接器)    | Circular Pin (圓型導體) | Brass                   | Tin-Plated                                       |
|                       | Base (膠座)           | Phenolic Bakelite (電木板) | UL 94V-0                                         |

3.0 Characteristic(產品特性):

| Item(項目) |                                        | Standard(標準規範)                                                                                                                                         |                                                    |                                                                     |                      |                       |
|----------|----------------------------------------|--------------------------------------------------------------------------------------------------------------------------------------------------------|----------------------------------------------------|---------------------------------------------------------------------|----------------------|-----------------------|
| 3.1      | 額定電流 Rated Current                     | Conductor Size                                                                                                                                         | AWG                                                | 18#                                                                 | 20#                  | 22#                   |
|          |                                        |                                                                                                                                                        | Area(mm <sup>2</sup> )                             | 0.82 mm <sup>2</sup>                                                | 0.52 mm <sup>2</sup> | 0.342 mm <sup>2</sup> |
|          |                                        | Amp AC/DC                                                                                                                                              |                                                    | 5A                                                                  |                      | 3A                    |
| 3.2      | 額定電壓 Rated Voltage                     | 250 V AC/DC                                                                                                                                            |                                                    |                                                                     |                      |                       |
| 3.3      | Ambient Temperature Range<br>環境與操作溫度範圍 | (操作使用溫度與濕度範圍) Operating Temp.: -25°C~+85°C ; 85% R.H. Max<br>Including 30°C Terminal Temperature Rise at rated Current ,<br>(包括定額電流內, 端子所產生 30°C 以下溫昇) |                                                    |                                                                     |                      |                       |
| 3.4      | Applicable Wire<br>適用電線                | 3.4.1                                                                                                                                                  | (金屬導體之型號) Conductor Construction Size: AWG #18~#22 |                                                                     |                      |                       |
|          |                                        | 3.4.2                                                                                                                                                  | (電線絕緣材質外徑) Wire Insulation O.D.: 1.60mm~2.90mm     |                                                                     |                      |                       |
| 3.5      | Storage of Package<br>包裝未拆封之保存         | Temperature and Humidity Condition<br>溫濕度條件                                                                                                            |                                                    | Temperature 溫度 : -10°C~+40°C<br>Percentage Humidity 相對濕度 : 70 % Max |                      |                       |
|          |                                        | Term<br>保存期限                                                                                                                                           | Housing                                            |                                                                     | 2 Years              |                       |
|          |                                        |                                                                                                                                                        | Crimp Terminal & Wafer                             |                                                                     | 1 Year               |                       |
| 3.6      | Floor Life 拆封後使用期限                     | Crimp Terminal & Wafer                                                                                                                                 |                                                    | 3 Months                                                            |                      |                       |



|                                                                                                                             |                              |                         |                                               |
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Note: 適用電路板厚度 Applicable Printed Circuit Board Thickness: 1.6 mm

4.0 Specimen(樣本圖示) :

| Part Name / Part Number / Picture or Photograph 零件名稱 / 零件型號 / 樣本圖示 |  |                                             |  |
|--------------------------------------------------------------------|--|---------------------------------------------|--|
| Wafer<br>Phenolic Bakelite<br>JS-1103-xx(B)                        |  | Housing<br>JS-1102                          |  |
| Crimp Terminal<br>Standard Feed<br>JS-1102-T                       |  | Crimp Terminal<br>Side Feed<br>JS-1102-T(L) |  |

5.0 Applicable Standards(適用規範):

ANSI/EIA 364 ; EIA/ECA 364 Testing method for electrical connectors.

電子連接器，所適用之 ANSI/EIA 364 ; EIA/ECA 364 測試規範

6.0 Mechanical Performance(機械性能):

| Item(項目) |                                                      | Test Condition(測試條件)                                                                                                                                | Requirement(規格)                         |
|----------|------------------------------------------------------|-----------------------------------------------------------------------------------------------------------------------------------------------------|-----------------------------------------|
| 6.1      | Insertion &<br>Withdrawal Force<br>嵌入力與拔出力           | Insert and withdrawal with connectors at the speed rate of 25 .4 ± 3 mm /minute. 連接器兩端勘合，以每一分鐘 25.4 ± 3mm 的速率，作嵌入與拔出往返測試<br>(EIA/ECA 364-13D)       | Refer to 9.1 Table1.<br>參照第 9.1 項 表格 1  |
| 6.2      | Wire Pullout<br>Force(Axial)<br>電線脫離端子包覆<br>之拔出力(軸向) | Pull out the cable from with contact terminal at the speed rate of 25 .4± 3 mm/minute. 對端子所包覆電線，施以每一分鐘 25 .4± 3 mm 速率之軸向拔出力<br>(CSA C22.2 No.182.3) | AWG#18 size wire 9.08kgf/Min.(89N 牛頓)   |
|          |                                                      |                                                                                                                                                     | AWG#20 size wire 4.54kgf/Min.(44.5N 牛頓) |
|          |                                                      |                                                                                                                                                     | AWG#22 size wire 3.62kgf/Min.(35.6N 牛頓) |



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| Item(項目)                                                            | Test Condition(測試條件)                                                                                                                                            | Requirement(規格)                                |
|---------------------------------------------------------------------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------|------------------------------------------------|
| 6.3<br>Crimp Terminal Retention Force ( in Housing )<br>柳線端子與膠座間拔出力 | Axial pullout force on the terminal in the housing at the speed rate of 25.4 ± 3 mm per minute. 對於已經存在於膠座當中柳線端子，施以每一分鐘 25.4 ± 3 mm 速率之軸向拔出力                     | 單一接觸點 Per Contact<br>最小容許值 <b>3.0 kgf/Min.</b> |
| 6.4<br>Circular Pin Retention Force( in Base )<br>圓型導體與膠座之間保持力      | Axial pullout force on the Circular pin in the base at the speed rate of 25.4 ± 3 mm per minute. (EIA/ECA 364-29C )<br>對於已經存在於膠座當中圓型導體，施以每一分鐘25.4 ± 3mm速率之軸向拔出力 | 單一接觸點 Per Contact<br>最小容許值 <b>1.5 kgf/Min.</b> |

7.0 Electrical Performance(電氣性能) :

| Item(項目)                                                        | Test Condition(測試條件)                                                                                                                                                                                                                                       | Requirement(規格)                                                              |
|-----------------------------------------------------------------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|------------------------------------------------------------------------------|
| 7.1<br>(Low –Signal Level)<br>Contact Resistance<br>(低階信號) 接觸阻抗 | A maximum voltage of 20mV and a maximum current of 100mA are applied to the mate connector. 對組合狀態下連接器，於其兩端施以最大測試電壓 20mV 以及最大測試電流 100mA (EIA/ECA 364-23C)<br>( Does not include wire resistance 不包含電線阻抗 )                                                   | Contact Resistance:<br><b>20 milliohms Max.</b><br>最大容許值. 20 毫歐姆             |
| 7.2<br>Insulation Resistance<br>絕緣阻抗                            | Apply 500V D/C for 1 minute between adjacent contacts to measure the insulation resistance. 對相鄰兩接觸導體，於一分鐘時間內施予 500V D/C 電壓，並量測其間絕緣阻抗值 (EIA 364-21C)                                                                                                        | Insulation Resistance:<br><b>Initial 1000 megohms Min</b><br>最初容許值. 1000 兆歐姆 |
| 7.3<br>Withstanding Voltage<br>耐電壓                              | Apply <b>1500 A/C (rms)</b> for 1 minute and the leakage current shall not exceed <b>0.5mA</b> to the adjacent terminal and ground of the mate connectors. 對組合狀態下連接器，於其相鄰兩導體末端各施以電壓 <b>1500 A/C (實效值)</b> 時間 1 分鐘，且漏電流必須小於 <b>0.5mA(毫安培)</b> (EIA 364-20C) | No breakdown or flashover.<br>無損毀或者產生火花                                      |



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8.0 Environmental Performance(環境性能) :

| Item(項目)                                                               | Test Condition(測試條件)                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                     | Requirement(規格)                                                                                                                                                                                                                                                          |
|------------------------------------------------------------------------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 8.1<br>Durability<br>耐久性                                               | Mate Connectors up <b>50</b> Cycles at a Maximun rate of <b>10</b> cycles Per minute prior to environmental test 以組合狀態下連接器且未經環境測試，依每分鐘內進行 <b>10</b> 次嵌入與拔出之最大速率，連續 <b>50</b> 次嵌入與拔出往返測試 (EIA/ECA 364-09C )                                                                                                                                                                                                                                                                                                                                                                                                                               | (After the test)<br>Contact resistance :<br><b>40 mΩ Max</b><br>經耐久性試驗後接觸阻抗<br>最大容許值 40 毫歐姆                                                                                                                                                                              |
| 8.2<br>Temperature Rise<br>(Via Current Cycling)<br>溫度上昇<br>(經由電流循環操作) | Mate connector . measure the temperature rise of contact when the maximum rated current is passed<br>以組合狀態下連接器，通過最大容許電流量測其導體溫度上昇值<br>(EIA 364-70B Conditions 1 . Method 1)                                                                                                                                                                                                                                                                                                                                                                                                                                                               | Mate connectors<br><b>Temperature Rise:</b><br><b>+30°C/Max.</b><br>組合狀態下之連接器溫度<br>上昇最大容許值+30°C                                                                                                                                                                          |
| 8.3<br>Vibration<br>耐振動                                                | A mated connector shall be mounted on a printed Circuit board and subjected to a vibration test of the following conditions. During the test, test current continuity shall be checked. After the test, contact resistance shall be measured.<br>以組合狀態下連接器焊接於電路板作為試驗樣品,依照隨附如下規格要求,進行耐振動試驗，試驗過程中確認是否產生不連續電流(斷電)現象，並於試驗過後量測其接觸阻抗。<br>(EIA/ECA 364-28E-Condition 1 )<br>Frequency(頻率) : 10~55~10 Hz/minute.<br>Amplitude (振幅) : 1.5 mm P-P<br>Direction (方向) :1. Axis of up and down.上下軸向(Y 軸)<br>2. Axis of right the left. 左右軸向(X 軸)<br>3. Axis of front and back.前後軸向(Z 軸)<br>Period(週期) : 2 hours for each direction.<br>(每一個軸向持續 2 小時) | Initial Contact Resistance :<br><b>20 milliohms Max.</b><br>接觸阻抗最初容許值 20 毫歐姆<br>(After the test)<br>Contact Resistance:<br><b>40 milliohms Max.</b><br>經耐振動試驗後接觸阻抗<br>最大容許值 40 毫歐姆<br><br>No discontinuity current is longer than 1 microsecond.<br>電流中斷現象，<br>時間不可多於1微秒 |



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| Item(項目) |                                    | Test Condition(測試條件)                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                               | Requirement(規格)                                                                                                              |
|----------|------------------------------------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|------------------------------------------------------------------------------------------------------------------------------|
| 8.4      | Humidity<br>(Steady State)<br>恆溫恆濕 | <p>A mated connector shall be placed in a humidity chamber of the following conditions. After the test, leave the specimen at room temperature for 1~2 hours before the contact resistance, the insulation resistance and the dielectric withstanding voltage shall be measured.</p> <p>(EIA 364-31B Conditions II . Method A)</p> <p>以組合狀態下連接器放置於恆定溫度與濕度的空間，依照隨附如下規格要求，進行恆溫恆濕試驗，經試驗過後將樣品置於室溫 1~2 小時，再量測其接觸阻抗、絕緣阻抗、以及耐電壓測試。</p> <p>Temperature(溫度) : 40±2°C.</p> <p>Relative Humidity(相對濕度) : 90%~95% (RH).</p> <p>Period(週期) : 96 hours continuously. (持續 96 小時)</p>                                                                                                                                                              | <p>(After the test)</p> <p>Contact Resistance:</p> <p><b>40 milliohms Max.</b></p> <p>經恆溫恆濕試驗後接觸阻抗<br/>最大容許值. 40 毫歐姆</p>     |
|          |                                    |                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                    | <p>(After the test)</p> <p>Insulation Resistance :</p> <p><b>500 Megohms Min.</b></p> <p>經恆溫恆濕試驗後絕緣阻抗<br/>最小容許值. 500 兆歐姆</p> |
|          |                                    |                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                    | <p>經恆溫恆濕試驗後測耐電壓</p> <p>(After the test)</p> <p>Withstanding Voltage:</p> <p><b>1500V A/C for 1 minute</b></p>                |
| 8.5      | Thermal Shock<br>冷熱衝擊              | <p>A mated connector shall be subjected to a thermal shock test of the following conditions. After the test, leave the specimen at room temperature for 1~2 hours before the contact resistance, the insulation resistance and the dielectric withstanding voltage shall be measured.</p> <p>以組合狀態下連接器作為試驗樣品，依照隨附如下規格要求，進行冷熱衝擊試驗，經試驗過後將樣品置於室溫 1~2 小時，再量測其接觸阻抗、絕緣阻抗、以及耐電壓測試。</p> <p>(EIA/ECA 364-32D Conditions I . Method A)</p> <p>One Cycle Consists Of:</p> <p><b>-55°C+0/-3°C for 30 minutes. → Room Temp. 5 minutes</b></p> <p><b>85°C+3/-0°C for 30 minutes. → Room Temp. 5 minutes</b></p> <p>Total Cycles: 5 Cycles.</p> <p>以-55°C+0/-3°C溫度持續 30 分鐘，經室溫 5 分鐘，而後再以 85°C+3/-0°C溫度持續 30 分鐘，再經室溫 5 分鐘，構成一次冷熱循環，總計循環次數 5 次。</p> | <p>Same as paragraph 8.4</p> <p>同 8.4 章節</p>                                                                                 |





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Certificate Number: PB 2824  
ISO 9002

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| Subject: JS-1102-xx JS-1103-xx(B) JS-1102-T JS-1102-T(L)<br>Pitch 5.00mm Series Wire to Board Power Connector |                                |                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                               |                                                                                                                                                                           | Issued By:<br>Engineering Dept. |
| Item(項目)                                                                                                      | Test Condition(測試條件)           |                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                               | Requirement(規格)                                                                                                                                                           |                                 |
| 8.6                                                                                                           | Thermal Aging<br>高溫老化試驗        | A mated connector shall be placed in a heat oven of the following conditions. After the test, leave the specimen at room temperature for 1~2 hours before the contact resistance shall be measured. 以組合狀態下連接器放置於加熱烤箱當中，依照隨附如下規格要求，進行高溫老化試驗，經試驗過後將樣品置於室溫 1~2 小時，再量測其接觸阻抗。<br>(EIA 364-17B Conditions 3 . Method A )<br>Temperature(溫度) : 85±2°C<br>Period(週期): 96 hours continuously . (持續 96 小時)                                                                                                                                                                              | Initial Contact Resistance :<br>20 milliohms Max.<br>接觸阻抗最初容許值 20 毫歐姆<br>(After the test)<br>Contact Resistance :<br>40 milliohms Max. .<br>經高溫老化試驗後接觸阻抗<br>最大容許值. 40 毫歐姆 |                                 |
| 8.7                                                                                                           | Cold 耐寒試驗<br>(Low Temperature) | A mated connector shall be placed in a cold chamber of the following conditions. After the test, leave the specimen at room temperature for 1~2 hours before the contact resistance shall be measured. 以組合狀態下連接器放置於低溫空間內，依照隨附如下規格要求，進行耐寒試驗，經試驗過後將樣品置於室溫 1~2 小時，再量測其接觸阻抗。<br>(EIA 364-59A Condition D ; Condition 4 )<br>Temperature(溫度) : -25±3°C.<br>Period(週期): 96 hours continuously . (持續 96 小時)                                                                                                                                                                          | Initial Contact Resistance :<br>20 milliohms Max.<br>接觸阻抗最初容許值 20 毫歐姆<br>(After the test)<br>Contact Resistance :<br>40 milliohms Max. .<br>經耐寒試驗後接觸阻抗<br>最大容許值. 40 毫歐姆   |                                 |
| 8.8                                                                                                           | Salt Spray<br>鹽水噴霧             | A mated connector shall be subjected to a Salt Spray test of the following conditions. After the test , the specimen shall be washed with running water and dried naturally before the measurement of contact resistance. 以組合狀態下連接器作為試驗樣品，依照隨附如下規格要求，進行鹽水噴霧試驗，試驗過後將樣品用清水沖洗並經過自然風乾，而後量測其接觸阻抗。<br>(EIA 364-26B Conditions B)<br>Density(鹽水密度): 5 % in weight.<br>Temperature(溫度): 35±2°C.<br>Period(週期): Terminal or contact (Stamping after tin plated for 8 hours ) ; Terminal or contact (Stamping before tin plated for 48 hours) 端子或導體(先電鍍後沖壓 8 小時) ; 端子或導體 (先沖壓後電鍍 48 小時) | Initial Contact Resistance :<br>20 milliohms Max.<br>接觸阻抗最初容許值 20 毫歐姆<br>(After the test)<br>Contact Resistance:<br>40 milliohms Max.<br>經鹽水噴霧試驗後接觸阻抗<br>最大容許值. 40 毫歐姆    |                                 |



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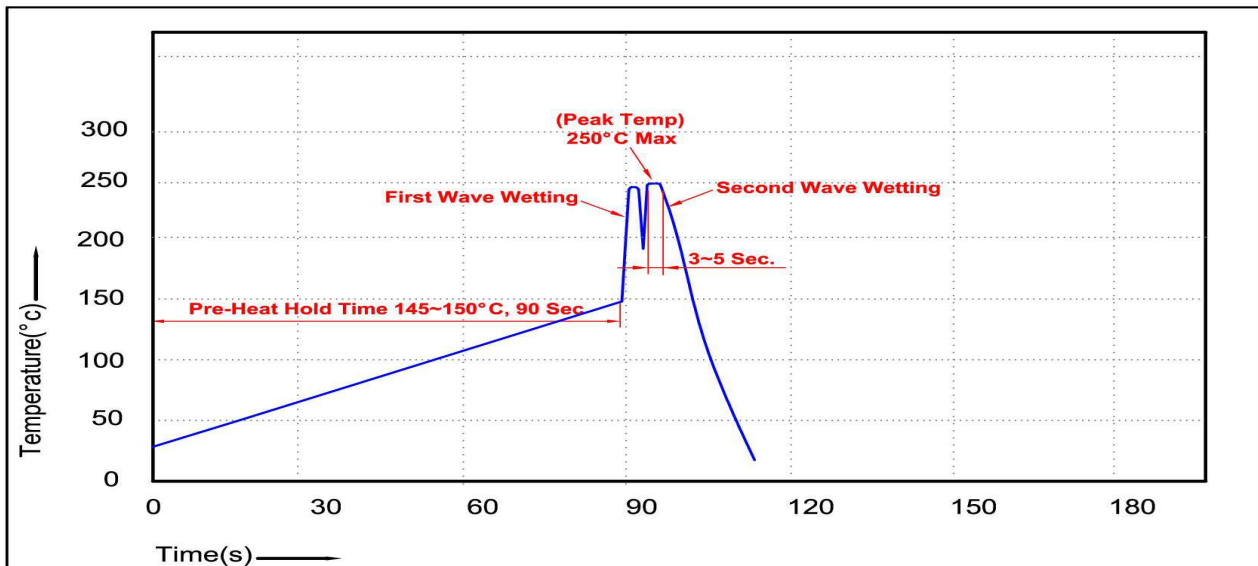
|                                                                                                                             |                              |                         |                                               |
|-----------------------------------------------------------------------------------------------------------------------------|------------------------------|-------------------------|-----------------------------------------------|
| <b>Type Document</b>                                                                                                        | <b>Product Specification</b> | <b>Revised /Edition</b> | <b>G</b>                                      |
| <b>Date Issued</b>                                                                                                          | <b>2005/05/05</b>            | <b>Data Revised</b>     | <b>2016/09/10</b>                             |
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| Item(項目)                                      | Test Condition(測試條件)                                                                                                                                                                                                                                                                                                                     | Requirement(規格)                                                                                   |
|-----------------------------------------------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|---------------------------------------------------------------------------------------------------|
| 8.9<br>Solder Ability<br>焊錫性                  | Fluxed soldering section of header shall be dipped in solder of the following conditions. 將連接器 pin 針基板嵌入端，接觸熱溶狀錫料，依照隨附如下規格要求，進行焊錫性試驗 (EIA 364-52B)<br>Solder Temperature (焊錫溫度) : $245 \pm 5^{\circ}\text{C}$ .<br>Immersion Period (沉浸週期) : $3 \pm 0.5$ Seconds<br>(操作方式) : 零件焊錫位置，距離導體末端 1.5mm<br>Method : 1.5mm from circular pin tip | Solder entirely 95% of immersed area must show no voids or pinholes.<br>焊料覆蓋面積必須達到 95%而且不能產生氣孔或空隙 |
| 8.10<br>Resistance to Soldering Heat<br>焊錫耐熱性 | By Wave Soldering(波焊適用溫度範圍) :<br>Refer to Temperature Profile 請參考 8.10.1 溫度曲線圖 (EIA-364-71B)                                                                                                                                                                                                                                             | No deformation or damage.<br>不可有變形或損壞                                                             |

Notes : Flowing Mixed Gas (EIA 364-65A) shall be conduct by Customer request 混合流動氣體測試依照客戶需求

8.10.1 Temperature Profile(溫度曲線圖) /

Wave Peak Soldering In-Lead Free Process 波焊無鉛制程







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|-----------------------------------------------------------------------------------------------------------------------------|------------------------------|-------------------------|-----------------------------------------------|
| <b>Type Document</b>                                                                                                        | <b>Product Specification</b> | <b>Revised /Edition</b> | <b>G</b>                                      |
| <b>Date Issued</b>                                                                                                          | <b>2005/05/05</b>            | <b>Data Revised</b>     | <b>2016/09/10</b>                             |
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9.0 Tables & Attachments

9.1 Table 1. Insertion Force (I.F.) & Withdrawal Force (W.F.) for user reference:

Unit : Kg/f

| No. of Circuits<br>極數 | AT INITIAL<br>首次嵌入與拔出(初始值) |                   | AT 50 <sup>TH</sup><br>50 次嵌入與拔出之後 | No. of Circuits<br>極數 | AT INITIAL<br>首次嵌入與拔出(初始值) |                   | AT 50 <sup>TH</sup><br>50 次嵌入與拔出之後 |
|-----------------------|----------------------------|-------------------|------------------------------------|-----------------------|----------------------------|-------------------|------------------------------------|
|                       | I.F. (MAX)<br>插入力          | W.F. (MIN)<br>拔出力 | W.F. (MIN)<br>拔出力                  |                       | I.F. (MAX)<br>插入力          | W.F. (MIN)<br>拔出力 | W.F. (MIN)<br>拔出力                  |
|                       | 01                         | 1.50              | 0.30                               |                       | 0.20                       | 04                | 6.00                               |
| 02                    | 3.00                       | 0.60              | 0.40                               | 05                    | 7.50                       | 1.50              | 1.00                               |
| 03                    | 4.50                       | 0.90              | 0.60                               | 06                    | 9.00                       | 1.80              | 1.20                               |

10.Remark(備註) : Any change or revision for the product specification will not be announced in advance.

Please contact our sales representative for the latest information.

有關規格書內容經變更或改版，如未能夠及時發佈與通知，煩請連絡我司業務人員以提供產品最新資訊

Reviewed: J.M.Chang Approved: Peter Chang Verified: Indiana Huang